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#### DYNAMIC MODULES -

# Part 6-2: Software and hardware interfaces – Survey results

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IEC 62343-6-2, which is a technical report, has been prepared by subcommittee 86C: Fibre optic systems and active devices, of IEC technical committee 86: Fibre optics.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting		
86C/880/DTR	86C/893/RVC		

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 62343 series, published under the general title *Dynamic modules,* can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "http://webstore.iec.ch" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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A bilingual version of this publication may be issued at a later date.

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#### DYNAMIC MODULES -

## Part 6-2: Software and hardware interfaces – Survey results

#### 1 Scope

This part of IEC 62343 clarifies dynamic module interfaces which should be standardized based on a survey of manufacturers. The objectives of this technical report are to present the survey results and to propose software (SW) and hardware (HW) interface standards of dynamic modules.

#### 2 Survey description

#### 2.1 Survey contents

The survey included the following items:

- a) Types of dynamic modules (supplier/user)
- b) Standards for the control interface that were offered in the past (from suppliers)
- c) Standards for the control interface that are planned in the future (from suppliers)
- d) Standards for the control interface that are requested (from users)
- e) Comments about the standards of typical control interfaces (from suppliers and users)
- f) Opinions about the standardization of control interfaces (from suppliers and users)

Annex A provides a summary of responses from Japan, Europe, and North America.

#### 2.2 Survey conditions

The survey conditions are as follows:

- a) Request to 55 companies
  (81 departments: users, suppliers, and representatives of suppliers)
- b) Received 28 kepties

Users: 12 companies Suppliers: 13 companies Both: 3 companies

c) Survey period From September to October, 2004

#### 3 Interface definitions

#### 3.1 General

The layer structure of the interface of a dynamic module is shown in Figure 1. There are an optical component and two microprocessors for control, and there are three interfacing points, Interface A, Interface B, and Interface C.

#### 3.2 Interface A

The interface A is the fundamental electrical interface portion of the core optical device and the optical component. It is, for example, an analogue interface, with the electric power directly impressed to a conductor or a motor. Moreover, it is thought that many proprietary specifications are changed to the TTL/CMOS level digital interfaces with this simple conversion circuit. This interface point is defined as the fundamental interface group.

#### 3.3 Interface B

As a second interface group, there are, for example, dual port RAM, I<sup>2</sup>C, etc. which are used at the interface B. These interfaces have spread widely and are adopted as a standard interface in the equipment by the system side.

#### 3.4 Interface C

The interface used at the interface C is classified into a third interface group. There is a bus that is specified by the system vendor. Ethernet and PCI/Compact-RCI bus are classified into this interface C.

#### 3.5 Other interfaces

In addition to this, traditional interfaces, such as GP-IB and R\$2326, are also classified as interface C. R\$485 and USB which are considered to be substitution of R\$232C are also classified into this. Since these interfaces are easy to use with a PC, they are used widely.



Figure 1 – Layer structure of dynamic module interface

#### 4 Survey results

#### 4.1 Types of dynamic modules

The survey results concerning the types of modules currently used are shown in Table 1. Types of dynamic modules include wavelength blockers, wavelength switches, and dynamic chromatic dispersion compensators.

Types of dynamic modules	Supplier	User
Wavelength blocker (W-blocker)	2	4
Wavelength switch (W-SW)	4	4
Variable optical attenuator-multiplexer (VOA-MUX)	4	4
Dynamic channel equalizer (DCE)	2	3
Dynamic gain equalizer (DGE) (including dynamic gain flattening filter)		5
Dynamic slope equalizer (DSE) (including dynamic gain tilt equalizer, variable slope attenuator)	2	3
Dynamic chromatic dispersion compensator (DCDC)	4	4
Dynamic polarization-mode dispersion compensator (DPMDC)	3	3
Tunable filter (TF) (including dynamic bandpass filter)	4	5
Variable optical attenuator, single channel type (VOAs)	8	11
Variable optical attenuator, array type (VOA-a)	7	5
Optical spatial switch, $1\times 2/2\times 2$ (O8W-12)	7	12
Optical spatial switch, MxN, 2 <m, (osw-mn)<="" 2<n="" td=""><td>7</td><td>5</td></m,>	7	5
Reconfigurable optical addrdrop multiplexers (ROADM)	90eb- <u>5</u> 38c7	$6324 \frac{1}{3} \frac{0}{100}$
Optical performance monitor (OPMON)	4	6
Arrayed waveguide grating with automatic temperature control (AWG)	3	6

NOTE This survey was carried out in 2004. In early 2007, the latest information of dynamic modules was investigated. Since 2004, WSS (wavelength selective switch) has been one of the most attractive dynamic modules. It is found out the software and hardware interface of WSS is only DP-RAM. Moreover, the other dynamic modules have continued to use almost the same interfaces as those in 2004.

#### 4.2 Standards of the control interface dealt in the past (from suppliers)

The survey results about standards of the control interface, which were dealt with in the past, are shown in Table 2. Various interfaces are used resulting from a demand from users, a proposal from suppliers, repair, support, or management because no standardization exists. RS232C is commonly adopted.

Interface	Number of companies	User demand	Supplier proposal	For management
Ethernet	2	3	0	0
l <sup>2</sup> C	4	3	3	0
SCSI	0	0	0	0
GP-IB	6	3	5	2
RS232C	10	5	16	4
RS485	2	1	1	1
USB	2	1	1	
Dual port RAM	4	2	5	
Shift register	0	0	0	0
VME bus	0	0	Ø	0
PCI/compact-PCI bus	1	0	1	
TTL/CMOS proprietary spec	4	2	2	0
Analogue control	3	0 (	$\gamma$	0
Motor controlled	4	3	3	0
ileh	STAK			

Table 2 – Standards of the control interface dealt in the past

#### 4.3 Potential future control interface standards (from suppliers)

The survey result about standards of the control interface which is planned to offer from now on is shown in Table 3. Various interfaces are planned because there is currently no standardization.

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Table 3 – Standards	of the cont	trol interfac	ce planned to be offered in the futu	liec-tr
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	Interface	Number of companies	User demand	Supplier proposal	Maintain same as before
	Ethernet	3	3	1	0
	l <sup>2</sup> C	3	2	0	1
$\langle \rangle$	scsi	0	0	0	0
	GP-NB	4	2	1	2
	RS232C	9	3	4	13
	RS485	2	1	0	1
	USB	4	1	3	0
	Dual port RAM	3	1	1	4
	Shift register	0	0	0	0
	VME bus	0	0	0	0
	PCI/compact-PCI bus	0	0	0	0
	TTL/CMOS proprietary spec	3	2	0	1
	Analog control	2	1	4	0
	Motor controlled	2	0	0	4